

COATING LIQUID FOR FORMING INSULATING FILM AND METHOD FOR  
PRODUCING INSULATING FILM

ABSTRACT

A coating liquid for forming insulating film which can form insulating film having high adhesion to semiconductor substrate is provided. The coating liquid for forming insulating film comprising following (A) and (B), wherein a water content in the coating liquid is not more than 1% by weight:

(A): a heat-reactive nonpolar compound or polymer thereof wherein the heat-reactive nonpolar compound is selected from the group consisting of a compound having not less than two C-C double bonds, a compound having not less than two C-C triple bonds and a compound having at least one C-C double bond and at least one C-C triple bond, (B): at least one compound selected from the group consisting of silane compounds represented by following formulae (1) to (3).